

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

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Email & Skype: info@chipsmall.com Web: www.chipsmall.com

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LI0805G301R-10

UNCONTROLLED DOCUMENT

PHYSICAL DIMENSIONS:

IMPEDANCE

IMPEDANCE

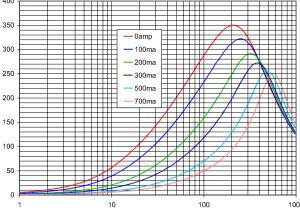
A 2.00 [.079] ± 0.20 [.008]

1.25 [.049] ± 0.20 [.008]

0.90 [.035] ± 0.20 [.008]

0.51 [.020] ± 0.25 [.010]

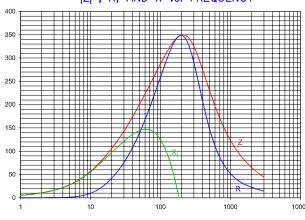
IMPEDANCE UNDER DC BIAS



Z vs FREQUENCY

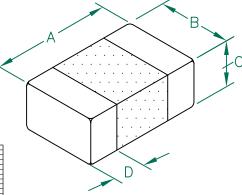


FREQUENCY (MHz)



FREQUENCY (MHz)

AGILENT E4991A RF Impedance/Material Analyzer HP 16194A Test Fixture. TEST REF. 3235



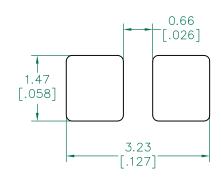


ELECTRICAL CHARACTERISTICS: Z @ 100MHz DCR Rated Current (Ω) (Ω) 300 Nominal Minimum 225 Maximum 375 0.2 700 mA

NOTES: UNLESS OTHERWISE SPECIFIED

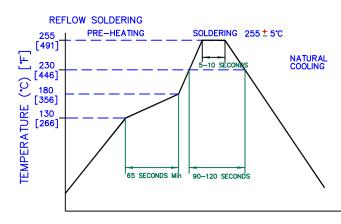
- 1. TAPED AND REELED per CURRENT EIA SPECIFICATIONS 7" REELS, 4000 PCS/REEL, PAPER TAPE.
- 2. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
- 3. TERMINATION FINISH IS 100% TIN.
- 4. OPERATING TEMP. RANGE: -40°C~+125°C. (INCLUDING SELF-HEATING)

LAND PATTERNS FOR REFLOW SOLDERING



(For wave soldering, add 0.763 [.030] to this dimension.)

RECOMMENDED SOLDERING CONDITIONS



2 of 2

DIMENSIONS ARE IN mm [INCHES].				This print is the property of Lair			
				Tech. and is loaned in confidence subject to return upon request of with the understanding that no copies shall be made without the	and e	a	ľ
				written consent of Laird Tech. Al rights to design or invention are			_
D	ADD OPERATING TEMPERATURE UPDATE LAIRD LOGO AND REFLOW CURVE	08/05/13	QU	reserved. PROJECT/PART NUMBER:	REV	PART TY	
С	CHANGE TO PAPER TAPE	03/04/10	JUN	LI0805G301R-10	ט ן	co-	FIRE
В	UPDATE COMPANY LOGO ADD ROHS SYM	07/21/08	JRK	DATE: 04/13/04	SCALE: N	TS	SHEE
Α	ORIGINAL DRAFT	04/13/04	JRK	, , ,	TOOL #	13	,
REV	DESCRIPTION	DATE	INT	"LI0805G301R-10-D	•	-	4